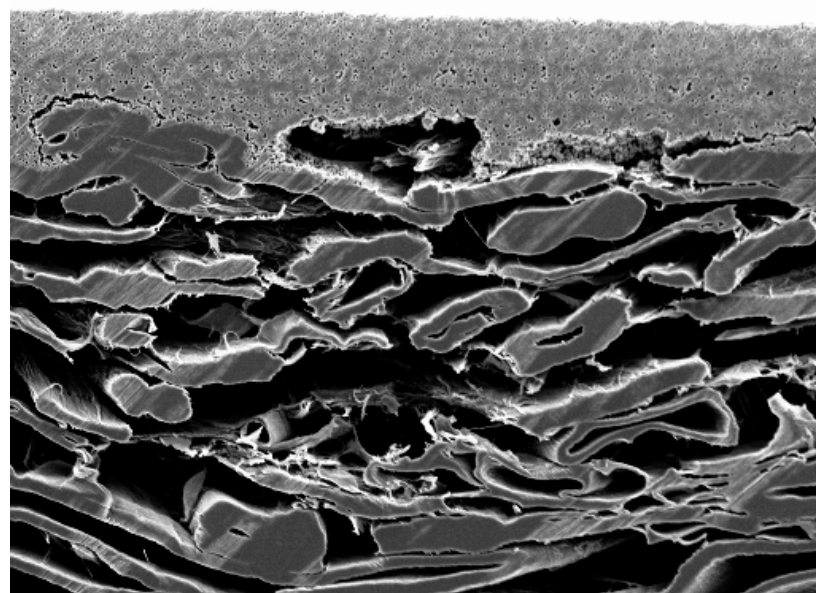
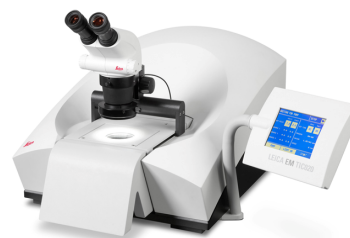


SEM MAG: 435 x      DET: SE  
HV: 5.0 kV          DATE: 05/09/08      200 um      Vega ©Tescan  
WD: 6.9720 mm      Device: RES120      BAL-TEC



SEM MAG: 1.45 kx      DET: SE  
HV: 5.0 kV          DATE: 05/09/08      50 um      Vega ©Tescan  
WD: 6.8703 mm      Device: RES120      BAL-TEC



## Leica EM TIC020 – Cross Section of Soft Cardboard

**Market: Paper industry, Research institutes**

Companies (e.g.): especially in Germany, Japan, USA, China, Xerox, Kanzan, Orio Consult, FiberMark Lahnstein etc.

Living up to Life

# Leica EM TIC020 Application No. 4/3

## Cross Section of Soft Cardboard

### Goal:

- Cross section of soft cardboard

### Process description (benchmark values for this particular sample):

Mechanical pre-preparation: Protection of the solar cell top

Parameter	
Acceleration voltage	7 kV
Gun current	2.6mA
Milling time	2.5 h
Cut depth	290 µm
Complete process time	3.5 h

### Results:

- Perfect cross section of the soft cardboard
- Information about the paper, the coating and their interface

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